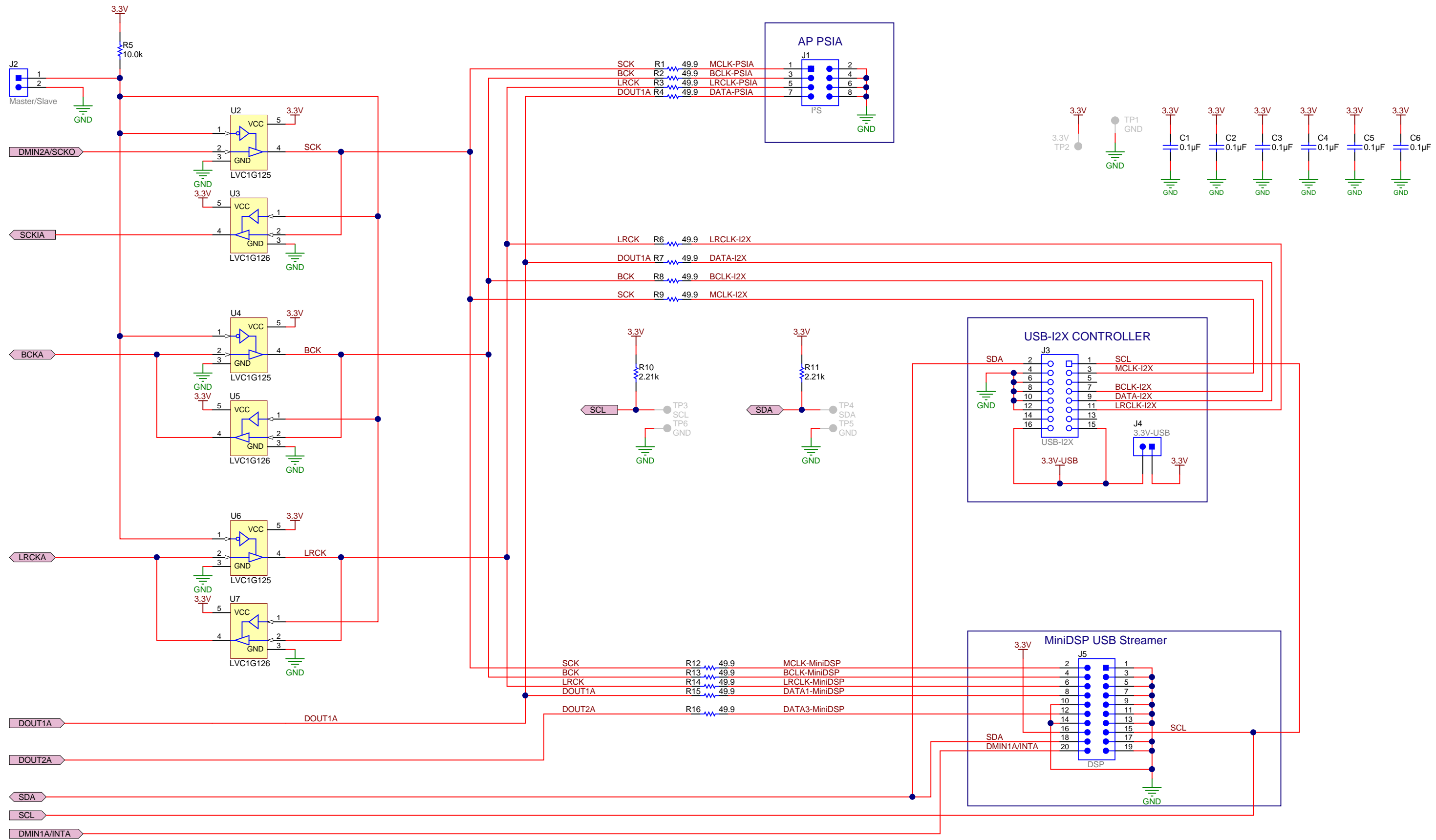


Orderable: PCM1864-REF1	Designed for: Public Release	Mod. Date: 5/12/2017
TID #: 01470	Project Title: PCM1864 Linear Microphone Board Reference Design	
Number: TIDA-01470	Sheet Title: Main I/O	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 3
Drawn By: LDN	File: TIDA-01470A_Main-I/O_SchDoc	Size: BC
Engineer: Ravi Patil	Contact: http://www.ti.com/support	Rev: A

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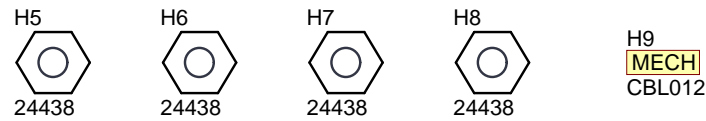




Orderable: PCM1864-REF1	Designed for: Public Release	Mod. Date: 5/12/2017
TID #: 01470	Project Title: PCM1864 Linear Microphone Board Reference Des	
Number: TIDA-01470	Rev: A	Sheet Title: DIGITAL I/O
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 3
Drawn By: LDN	File: TIDA-01470A_DIG-IO_SchDoc	Size: B
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PCB Number: TIDA-01470
PCB Rev: A

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PCB LOGO
Pb-Free Symbol

PCB LOGO
FCC disclaimer

ZZ1
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ2
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ3
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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Orderable: PCM1864-REF1	Designed for: Public Release	Mod. Date: 5/12/2017
TID #: 01470	Project Title: PCM1864 Linear Microphone Board Reference Des	
Number: TIDA-01470	Rev: A	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 3 of 3
Drawn By:	File: TIDA-01470A_Hardware.SchDoc	Size: Letter
Engineer: Ravi Patil	Contact: http://www.ti.com/support	



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